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### **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31A225KB9LNNC

• Product : Multi-layer Ceramic Capacitor • Descriptiont : CAP, 2.2 µF, 50V, ±10%, X5R, 1206

#### A. Samsung Part Number

<u>CL</u> <u>31</u> <u>A</u> <u>225</u> <u>K</u> <u>B</u> <u>9</u> <u>L</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	1206 (inch code)	L: 3.2 ± 0.2 mm W	': 1.6 ± 0.2 mm
		Thickness division	Low profile
3 Dielectric	X5R	Inner electrode	Ni
4 Capacitance	<b>2.2</b> μF	Termination	Cu
⑤ Capacitance	±10 %	Plating	Sn 100% (Pb Free)
tolerance		Product	Normal
Rated Voltage	50 V	Special	Reserved for future use
7 Thickness	0.9 ± 0.1 mm	① Packaging	Cardboard Type, 7" reel

#### **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition	
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms	
Tan δ (DF)	0.1 max.		
Insulation	10,000Mohm or 100Mohm⋅μF	Rated Voltage 60~120 sec.	
Resistance	Whichever is Smaller		
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding	No dielectric breakdown or	250% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	X5R		
Characterisitcs	(From -55 $^{\circ}\!$		
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)	
		with 1.0mm/sec.	
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder	
	is to be soldered newly	245±5℃, 3±0.3sec.	
		(preheating : 80~120 ℃ for 10~30sec.)	
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.	
Soldering heat	Tan δ, IR : initial spec.		

	Performance		Test condition
Vibration Test	Capacitance change: with	hin ±5%	Amplitude: 1.5mm
	Tan δ, IR : initial spec.		From 10Hz to 55Hz (return : 1min.)
			2hours $\times$ 3 direction (x, y, z)
Moisture	Capacitance change: with	hin ±12.5%	With rated voltage
Resistance	Tan δ: 0.125 max		40±2℃, 90~95%RH, 500+12/-0hrs
	IR : 12.5MΩ·μF or Over		
High Temperature	Capacitance change : with	hin ±12.5%	With 150% of the rated voltage
Resistance	Tan δ: 0.125 max		Max. operating temperature
	IR : 25MΩ·μF or Over		
			1000+24/-0hrs
Temperature	Capacitance change: with	hin ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.		Min. operating temperatur → 25°C
			→ Max. operating temperature → 25°C
			5 cycle test

#### C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}\text{C}\,,$  10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.